Appl. No. 10/743,985 Amdt. dated 02/28/2007 Response to Office Action of 11/28/2006 Attorney Docket No.: N1085-00168 [TSMC 2003-0219]

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

- 1 1 10. (Cancelled)
- 1 11. (Currently Amended): An SOI device having a gate, comprising:
- oxygen ions providing <u>discrete</u> implant[[s]] <u>regions</u> in a substrate of an SOI device, the <u>discrete</u> implant <u>regions</u> extending to a <u>surface</u> of the <u>substrate</u>; and
- one or more additional gate regions covering all <u>discrete</u> implant[[s]] <u>regions</u>
 under the one or more additional gate regions, <u>and</u>
- a gate oxide layer covering but not encroaching the discrete implant regions and
 being under the one or more additional gate regions.
- the ions forming-thicker-gate-exide regions, and reducing substrate resistance under each of the additional gate regions.
- 1 12. (Original): The SOI device as recited in claim 11, further comprising:
- 2 implanted ions in the substrate, the one or more additional gate regions covering 3 the implanted ions.
- 1 13. (Currently Amended) The SOI device as recited in claim 11, further comprising; a
- 2 wherein the gate oxide layer has the same thickness over the discrete implant regions
- 3 and over regions other than the discrete implant regions covering the ions and being
- 4 under the one or more additional gate regions.
- 1 14. (Currently Amended): The SOI device as recited in claim 11, further comprising:
- 2 a gate of the SOI device;
- 3 a gate oxide under the gate and under the one or more additional gate regions;
- 4 and
- 5 the gate exide covering the ions.

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- 1 15. (Currently Amended): The SOI device as recited in claim 11, further comprising:
- 2 a gate electrode layer forming an SOI device gate and the one or more additional
- 3 gate regions; and
- 4 a gate oxide layer under the gate and under the one or more additional gate
- 5 regions.
- 1 16. (Currently Amended): The SOI device as recited in claim 11, further comprising:
- an SOI device gate and the one or more additional gate regions being formed
- 3 from a gate electrode layer; and
- 4 a gate oxide layer wherein the gate oxide layer is under the gate and under the
- 5 one or more additional gate regions.
- 1 17. (Currently Amended): The SOI device as recited in claim 11, further comprising:
- 2 the gate oxide layer including a thin gate oxide layer, having and a thicker gate
- 3 oxide layer covering the ions discrete implant regions;
- an SOI device gate on the thin gate oxide layer; and
- the one or more additional gate regions being on the thicker gate oxide layer.
- 1 18. (Currently Amended): The SOI device as recited in claim 11, further comprising:
- 2 the thicker gate oxide <u>layer</u> being a selective epitaxy growth.
- 1 19. (Original): The SOI device as recited in claim 11, further comprising:
- 2 the substrate having an STI enclosure for the ions.
- 1 20-35. (Cancelled)
- 1 36. (New): An SOI device having a gate, comprising:
- 2 oxygen ions providing discrete implant regions in a substrate of an SOI device,
- 3 the discrete implant regions extending to a surface of the substrate;

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one or more additional gate regions covering the discrete implant regions, and, a gate oxide layer covering the discrete implant regions and being under the one or more additional gate regions, the gate oxide layer having the same thickness over the discrete implant regions and over regions other than the discrete implant regions, the ions reducing substrate resistance under each of the additional gate regions.